features

- 60 MSPS Maximum Sample Rate
- 10-Bit Resolution
- No Missing Codes
- On-Chip Sample and Hold
- 73 dB Spurious Free Dynamic Range at f_{in} = 15.5 MHz
- 5 V Analog and Digital Supply
- 3 V and 5 V CMOS Compatible Digital Output
- 9.5 Bit ENOB at f_{IN} = 31 MHz
- 60 dB SNR at f_{IN} = 31 MHz
- 82 MHz Bandwidth
- Internal or External Reference
- Buffered 900 Ω Differential Analog Input

applications

- Wireless Local Loop
- Wireless Internet Access
- Cable Modem Receivers
- Medical Ultrasound
- Magnetic Resonant Imaging

description

The THS1060 is a high speed low noise 10-bit CMOS pipelined analog-to-digital converter. A differential sample and hold minimizes even order harmonics and allows for a high degree of common mode rejection at the analog input. A buffered analog input allows for operation with a constant analog input impedance, and prevents transient voltage spikes from feeding backward to the analog input source. Full temperature DNL performance allows for industrial application with the assurance of no missing codes. The THS1060 can operate with either internal or external references. Internal reference usage selection is accomplished simply by externally connecting reference output terminals to reference input terminals. Packaged in a small 48-pin quad flat-pack, the THS1060 makes use of Texas Instruments PowerPAD™ technology. The die of the THS1060 is bonded directly to a copper alloy plate which is exposed on the bottom of the package. When soldered to a ground land, the PowerPAD™ provides superior heat dissipation and thermal performance ideal for industrial applications in high temperature environments.



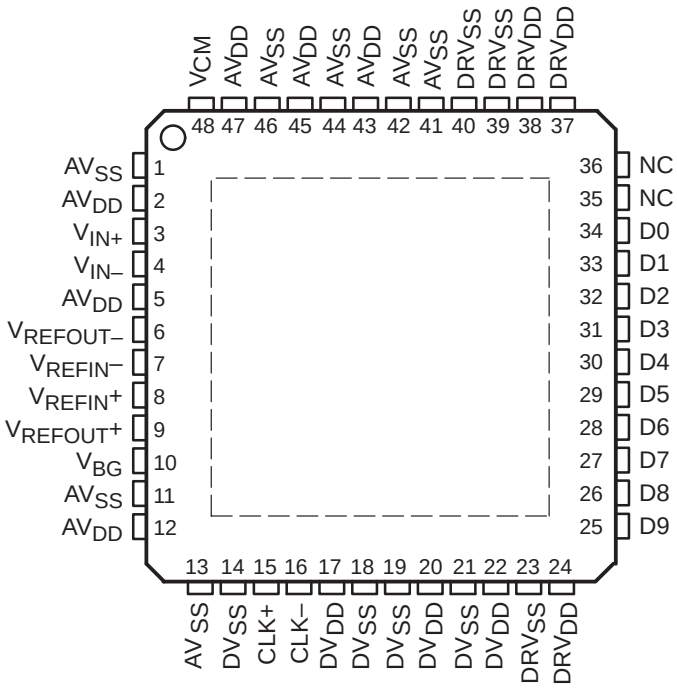
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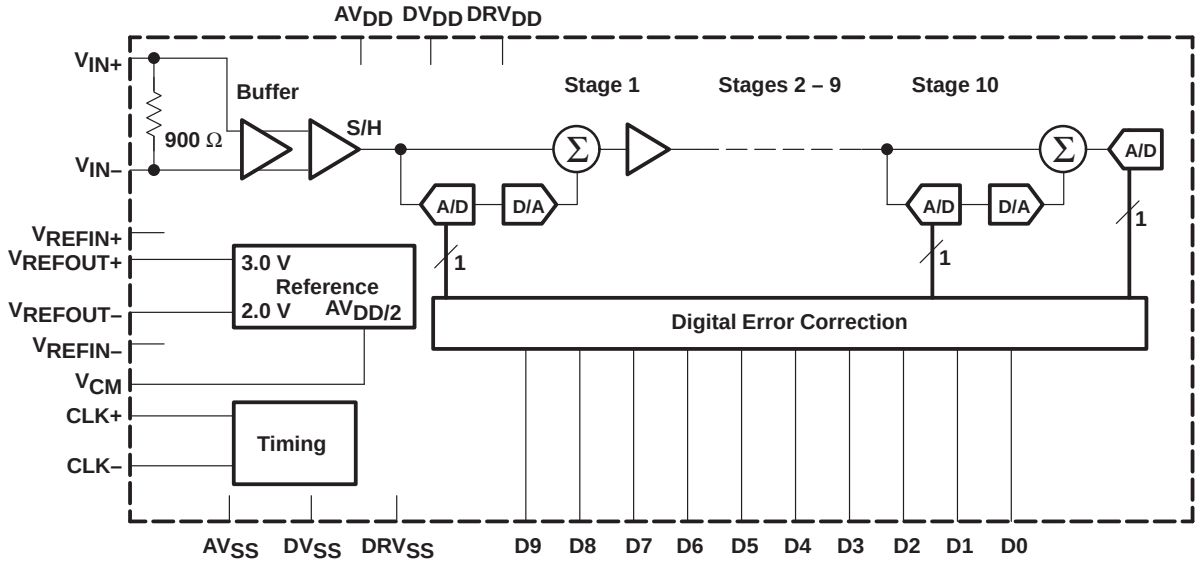
48 PHP PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T_A	PACKAGE
	48-TQFP (PHP)
–40°C to 85°C	THS1060I
0°C to 70°C	THS1060C

functional block diagram



Terminal Functions

TERMINAL NAME	TERMINAL NO.	I/O	DESCRIPTION
AV_{DD}	2, 5, 12 43, 45, 47	I	Analog power supply
AV_{SS}	1, 11, 13, 41, 42, 44, 46	I	Analog ground return for internal analog circuitry
CLK+	15	I	Clock input
CLK–	16	I	Complementary clock input
D9–D0	25–34	O	Digital data output bits; LSB= D0, MSB = D9 (2s complement output format)
DRV_{DD}	24, 37, 38	I	Digital output driver supply
DRV_{SS}	23, 39, 40	I	Digital output driver ground return
DV_{DD}	17, 20, 22	I	Positive digital supply
DV_{SS}	18, 19, 21	I	Digital ground return
V_{BG}	10	O	Band gap reference. Bypass to ground with a 1 μF and a 0.01 μF chip capacitor.
V_{CM}	48	O	Common mode voltage output. Bypass to ground with a 0.1 μF and a 0.01 μF chip device capacitor.
V_{IN+}	3	I	Analog signal input
$V_{IN–}$	4	I	Complementary analog signal input
$V_{REFIN–}$	7	I	External reference input low
V_{REFIN+}	8	I	External reference input high
$V_{REFOUT+}$	9	O	Internal reference output. Compensate with a 1 μF and a 0.01 μF chip capacitor.
$V_{REFOUT–}$	6	O	Internal reference output. Compensate with a 1 μF and a 0.01 μF chip capacitor.

detailed description

The THS1060 uses a differential pipeline architecture and assures no missing codes over the full operating temperature range. The device uses a 1 bit per stage architecture in order to achieve the highest possible bandwidth. The differential analog inputs are terminated with a 900 Ω resistor. The inputs are then fed to a unity gain buffer followed by the S/H (sample and hold) stage. This S/H stage is a switched capacitor op-amp based circuit, see Figure 3. The pipeline is a typical 1 bit per stage pipeline as shown in the functional block diagram. The digital output of the 10 stages and the last 1 bit flash are sent to a digital correction logic block which then outputs the final 10 bits.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range: AV_{DD} . . . . . –0.5 V to 7 V
DV_{DD} . . . . . –0.5 V to 7 V
DRV_{DD} . . . . . –0.5 V to 7 V
Voltage between AV_{SS} and DV_{SS} . . . . . –0.3 V to 0.5 V
Voltage between DRV_{DD} and DV_{DD} . . . . . –0.5 V to 5 V
Voltage between AV_{DD} and DV_{DD} . . . . . –0.5 V to 5 V
Digital data output . . . . . –0.3 V to DV_{DD} +0.3 V
CLK peak input current . . . . . 20 mA
Peak total input current (all inputs) . . . . . –30 mA
Operating free-air temperature range, T_A: THS1060C . . . . . 0°C to 70°C
THS1060I . . . . . –40°C to 85°C
Storage temperature range . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

PARAMETER		MIN	NOM	MAX	UNIT
Sample rate		1		60	MSPS
Analog supply voltage, AV_{DD}		4.75	5	5.25	V
Digital supply voltage, DV_{DD}		4.75	5	5.25	V
Digital output driver supply voltage, DRV_{DD}		3	3.3	5.25	V
CLK + high level input voltage, V_{IH}		4	5	5.5	V
CLK + low-level input voltage, V_{IL}			0	1	V
CLK – high-level input voltage, V_{IH}		4	5	5.5	V
CLK – low-level input voltage, V_{IL}			0	1	V
CLK pulse-width high, $t_{p(H)}$		7.5	8.3		ns
CLK pulse-width low, $t_{p(L)}$		7.5	8.3		ns
Operating free-air temperature range, T_A	THS1060C	0		70	°C
Operating free-air temperature range, T_A	THS1060I	–40		85	°C

electrical characteristics, over recommended operating free-air temperature range, AV_{DD} = DV_{DD} = 5 V, DRV_{DD} = 3.3 V, internal references, CLK = 60 MHz, (unless otherwise noted)‡

dc accuracy

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
DNL	Differential nonlinearity (see Note 1)			±0.4	±1	LSB
	No missing codes (see Note 2)			Assured		
INL	Integral nonlinearity (see Note 1)			±0.9	±3	LSB
E_O	Offset error			15	31	mV
E_G	Gain error			–7	–10	%FSR

‡ All typical values are at T_A = 25°C.

NOTES: 1. Tested without over ranging
2. Tested with over ranging

electrical characteristics, over recommended operating free-air temperature range, AV_{DD} = DV_{DD} = 5 V, DRV_{DD} = 3.3 V, internal references, CLK = 60 MHz, (unless otherwise noted)†

power supply

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I(AV_{DD})$	Analog supply current	$V(V_{IN}) = V(V_{CM})$		120	150	mA
$I(DV_{DD})$	Digital supply current	$V(V_{IN}) = V(V_{CM})$		2	5	mA
$I(DRV_{DD})$	Output driver supply current	$V(V_{IN}) = V(V_{CM})$		2	6	mA
P_D	Power dissipation	$V(V_{IN}) = V(V_{CM})$		0.6		W

† All typical values are at T_A = 25°C.

reference

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$V_{REFOUT-}$	Negative reference output voltage		1.95	2	2.05	V
$V_{REFOUT+}$	Positive reference output voltage		2.95	3	3.05	V
V_{REFIN-}	External reference supplied			2		V
V_{REFIN+}	External reference supplied			3		V
$V(V_{CM})$	Common mode output voltage			$AV_{DD}/2$		V
$I(V_{CM})$	Common mode output current			10		μA

† All typical values are at T_A = 25°C.

analog input

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
R_I	Differential input resistance			900		Ω
C_I	Differential input capacitance			4		pF
V_I	Analog input common mode range			$V_{CM} \pm 0.05$		V
V_{ID}	Differential input voltage range			2		V p-p
BW	Analog input bandwidth (large signal)	–3 dB		82		MHz

† All typical values are at T_A = 25°C.

digital outputs

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	I_{OH} = –50 μA	$0.8DRV_{DD}$			V
V_{OL}	Low-level output voltage	I_{OL} = 50 μA			$0.2DRV_{DD}$	V_{DD}
C_L	Output load capacitance				15	pF

† All typical values are at T_A = 25°C.

ac specifications, over recommended operating free-air temperature range, AV_{DD} = DV_{DD} = 5 V, DRV_{DD} = 3.3 V, internal references, CLK = 60 MHz, analog input at –2 dBFS(unless otherwise noted)†

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SNR	Signal to noise ratio	f_{IN} = 2.2 MHz		60		dBFS
		f_{IN} =15.5 MHz	56	60		
		f_{IN} =31 MHz		60		
SINAD	Signal to noise and distortion	f_{IN} = 2.2 MHz		59		dBFS
		f_{IN} =15.5 MHz	53	59.6		
		f_{IN} =31 MHz		59		
ENOB	Effective number of bits	f_{IN} =15.5 MHz	8.5	9.6		bits
THD	Total harmonic distortion	f_{IN} =15.5 MHz		–72	–54	dBc
SFDR	Spurious-free dynamic range	f_{IN} =15.5 MHz	57	73		
2^{nd} Harmonic	Distortion	f_{IN} = 2.2 MHz		–80		dBc
		f_{IN} =15.5 MHz		–77	–57	
		f_{IN} = 31 MHz		–79		
3^{rd} Harmonic	Distortion	f_{IN} = 2.2 MHz		–68		dBc
		f_{IN} =15.5 MHz		–79	–60	
		f_{IN} = 31 MHz		–68		
Two tone SFDR		F1 = 14.9 MHz, F2 = 15.6 MHz, Analog inputs at – 8 dBFS each		70		dBc

† All typical values are at T_A = 25°C.

operating characteristics over recommended operating conditions, AV_{DD} = DV_{DD} = 5 V, DRV_{DD} = 3.3 V

switching specifications

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Aperture delay, $t_{d(A)}$			120		ps
Aperture jitter			1		ps RMS
Output delay $t_{d(O)}$	After falling edge of CLK+			13	ns
Pipeline delay $t_{d(PIPE)}$			6.5		CLK Cycle

definitions of specifications

analog bandwidth
The analog input frequency at which the spectral power of the fundamental frequency of a large input signal is reduced by 3 dB.

aperture delay
The delay between the 50% point of the rising edge of the clock and the instant at which the analog input is sampled.

aperture uncertainity (jitter)
The sample-to-sample variation in aperture delay

differential nonlinearity
The average deviation of any output code from the ideal width of 1 LSB.

clock pulse width/duty cycle
Pulse width high is the minimum amount of time that the clock pulse should be left in logic 1 state to achieve rated performance; pulse width low is the minimum time clock pulse should be left in low state. At a given clock rate, these specs define acceptable clock duty cycles.

offset error
The difference between the analog input voltage at which the analog-to-digital converter output changes from negative full scale, to one LSB above negative full scale, and the ideal voltage at which this transition should occur.

gain error
The maximum error in LSBs between a digitized ideal full scale low frequency offset corrected triangle wave analog input, from the ideal digitized full scale triangle wave, divided by the full scale range, in this case 1024.

harmonic distortion
The ratio of the power of the fundamental to a given harmonic component reported in dBc.

integral nonlinearity
The deviation of the transfer function from an end-point adjusted reference line measured in fractions of 1 LSB. Also the integral of the DNL curve.

output delay
The delay between the 50% point of the falling edge of the clock and signal and the time when all output data bits are within valid logic levels (not including pipeline delay).

signal-to-noise-and distortion (SINAD)
When tested with a single tone, the ratio of the signal power to the sum of the power of all other spectral components, excluding dc, referenced to full scale.

signal-to-noise ratio (SNR)
When tested with a single tone, the ratio of the signal power to the sum of the power of all other power spectral components, excluding dc and the first 9 harmonics, referenced to full scale.

effective number of bits (ENOB)

For a sine wave, SINAD can be expressed in terms of the number of bits, using the following formula,

$$\text{ENOB} = \frac{(\text{SINAD} - 1.76)}{6.02}$$

spurious-free dynamic range (SFDR)
The ratio of the signal power to the power of the worst spur, excluding dc. The worst spurious component may or may not be a harmonic. The ratio is reported in dBc (that is, degrades as signal levels are lowered).

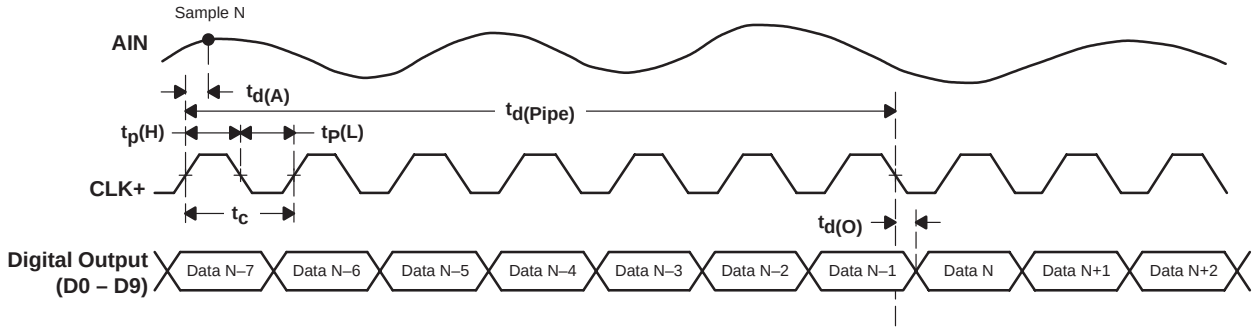


Figure 1. Timing Diagram

equivalent circuits

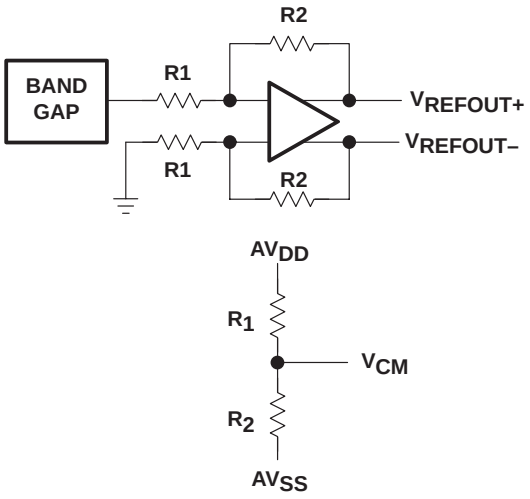


Figure 2. References

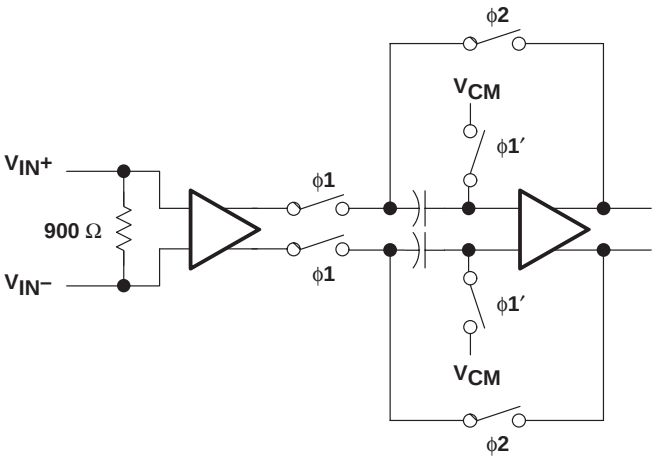


Figure 3. Analog Input Stage

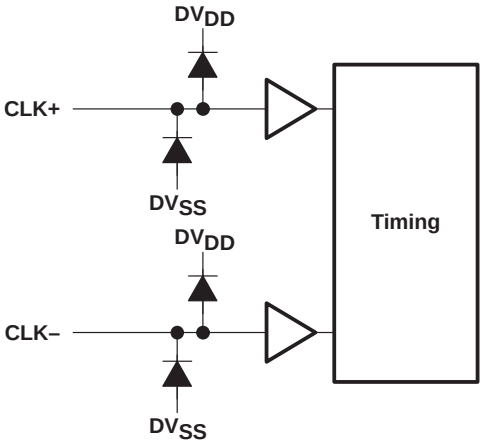


Figure 4. Clock Inputs

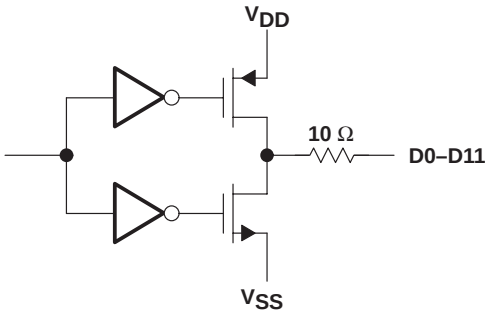


Figure 5. Digital Outputs

TYPICAL CHARACTERISTICS†

**OUTPUT POWER SPECTRUM
vs
FREQUENCY**

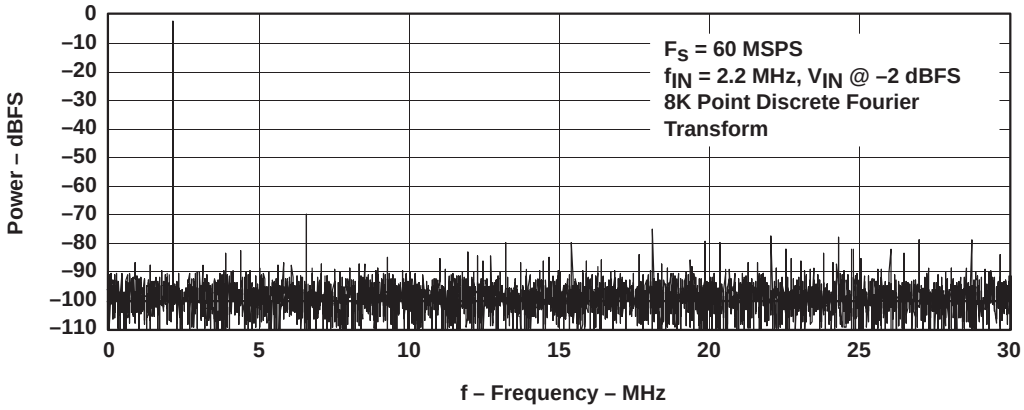


Figure 6

**OUTPUT POWER SPECTRUM
vs
FREQUENCY**

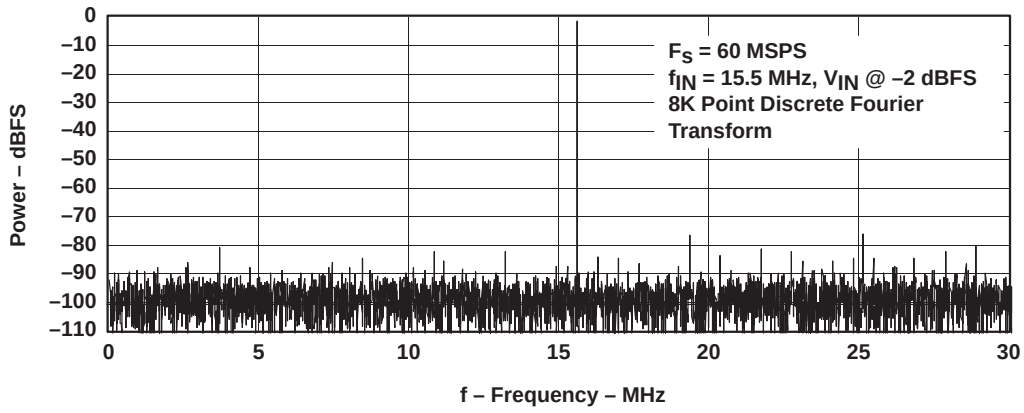


Figure 7

† AV_{DD} = 5 V, DV_{DD} = 5 V, DRV_{DD} = 3.3 V, T_A = 25°C (unless otherwise noted)

TYPICAL CHARACTERISTICS

OUTPUT POWER SPECTRUM
vs
FREQUENCY

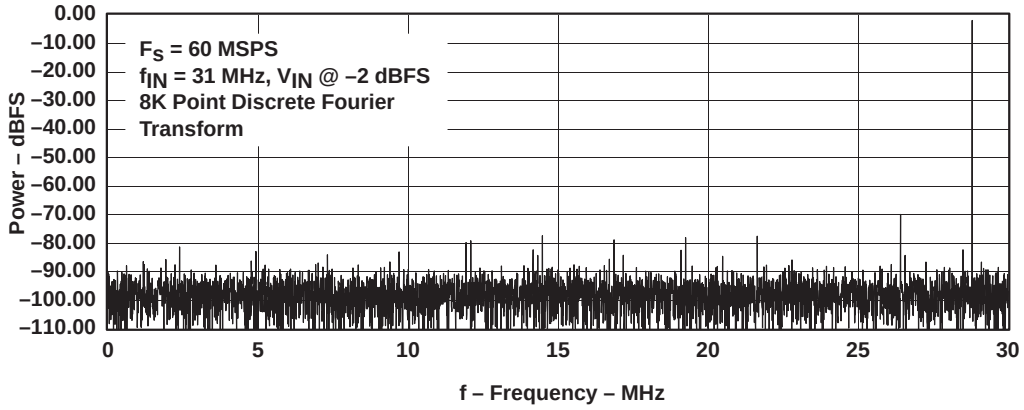


Figure 8

OUTPUT POWER SPECTRUM
vs
FREQUENCY

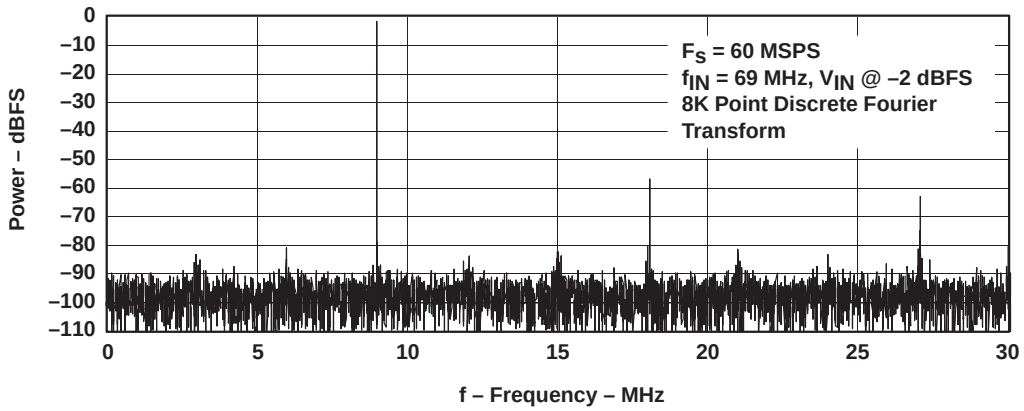


Figure 9

TYPICAL CHARACTERISTICS

**NOISE AND DISTORTION
vs
ANALOG INPUT FREQUENCY**

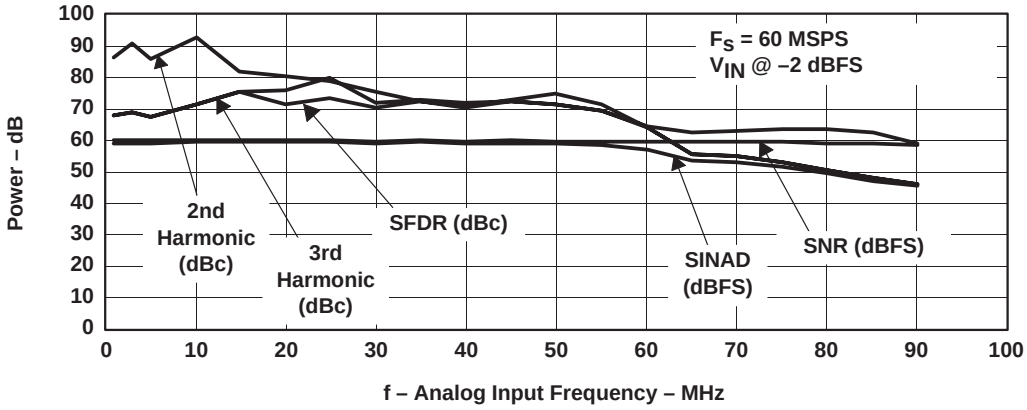


Figure 10

**TWO-TONE OUTPUT POWER SPECTRUM
vs
FREQUENCY**

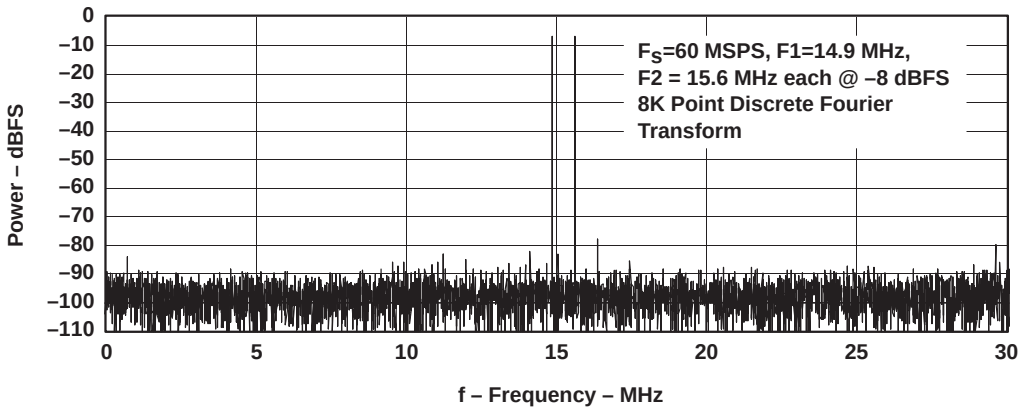


Figure 11

TYPICAL CHARACTERISTICS

**NOISE AND DISTORTION
vs
ANALOG INPUT POWER LEVEL**

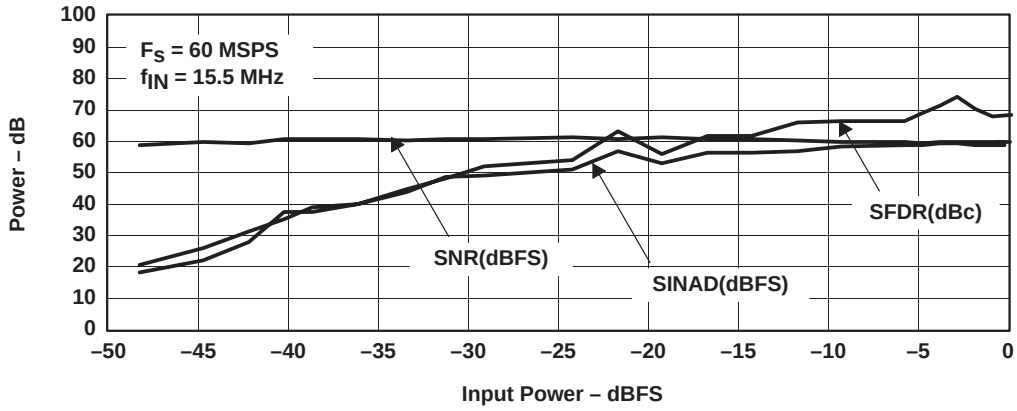


Figure 12

**NOISE AND DISTORTION
vs
CLOCK FREQUENCY**

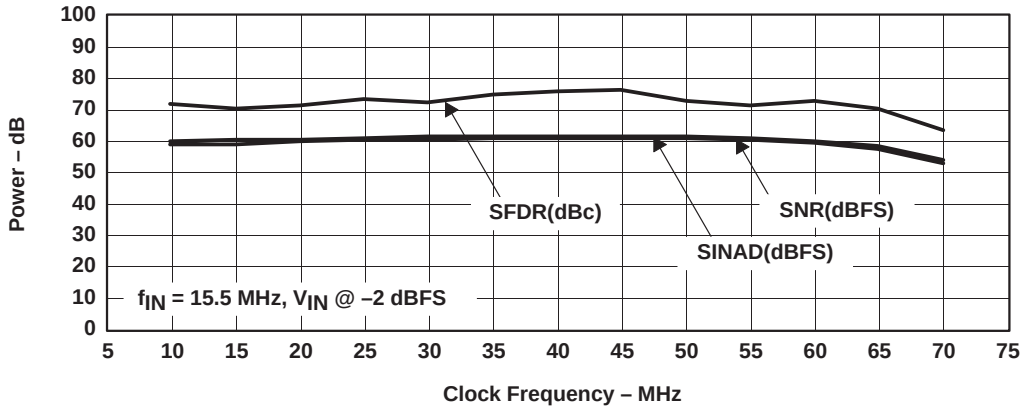


Figure 13

TYPICAL CHARACTERISTICS

**NOISE AND DISTORTION
vs
DUTY CYCLE**

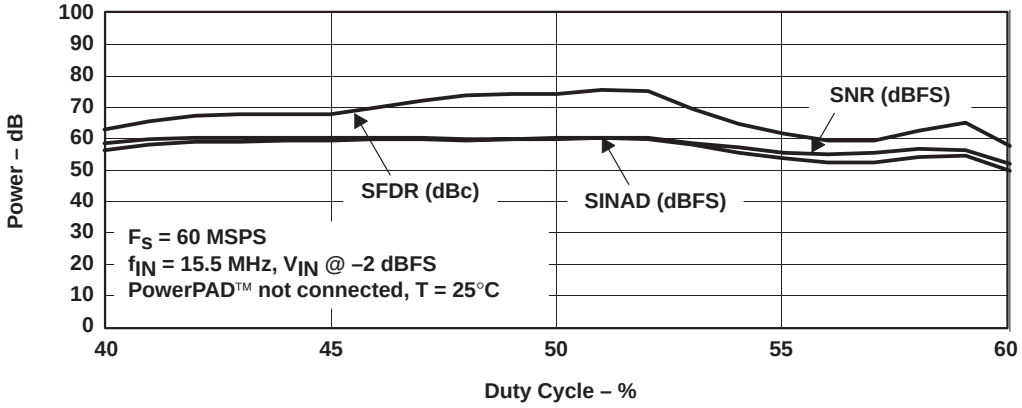


Figure 14

**DIFFERENTIAL NONLINEARITY
vs
OUTPUT CODE**

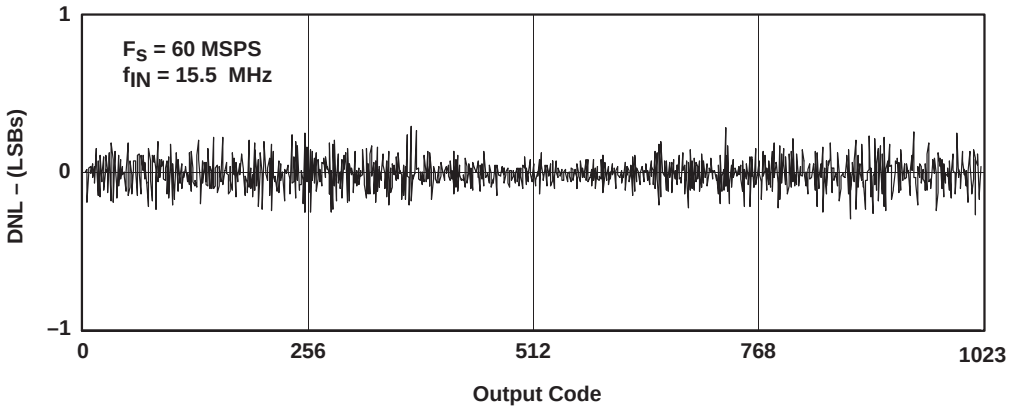


Figure 15

TYPICAL CHARACTERISTICS

INTEGRAL NONLINEARITY vs OUTPUT CODE

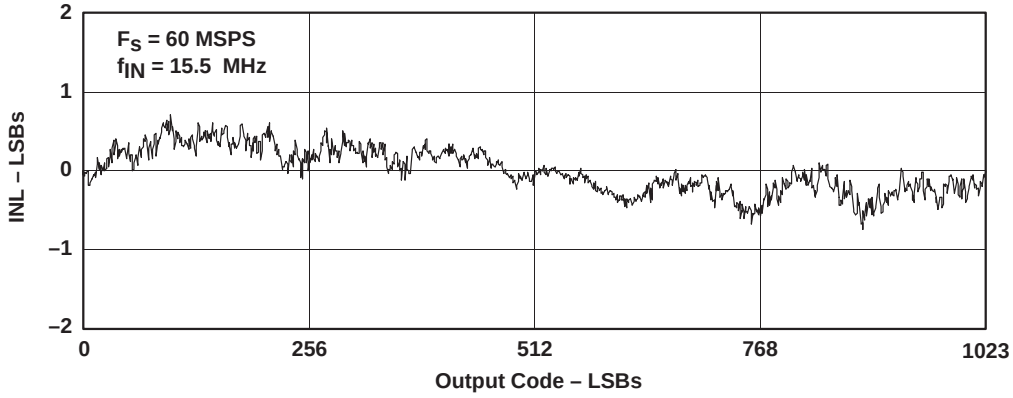


Figure 16

LARGE SIGNAL ANALOG INPUT BANDWIDTH

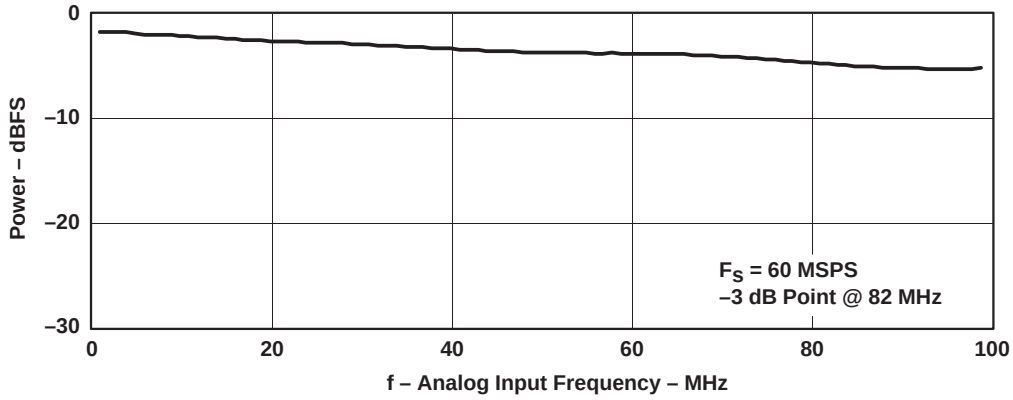


Figure 17

PERFORMANCE vs DUTY CYCLE WITH PowerPAD™

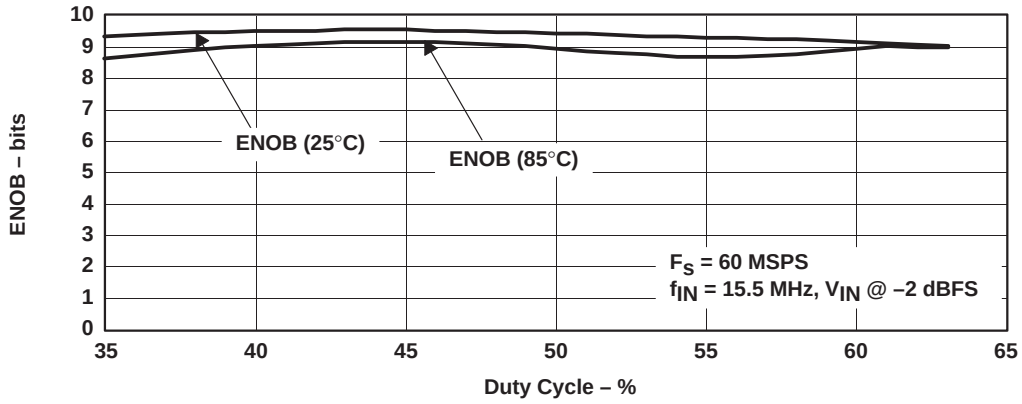


Figure 18

APPLICATION INFORMATION

using the THS1060 references

The option of internal or external reference is provided by allowing for an external connection of the internal reference to the reference inputs. This type of reference selection offers the lowest noise possible by not relying on any active switch to make the selection. Compensating each reference output with a 1-μF and 0.01 μF microwave chip capacitor is required as shown in Figure 19. The differential analog input range is equal to 2 ($V_{REFOUT+} - V_{REFOUT-}$). When using external references, it is best to decouple the reference inputs with a 0.1 μF and 0.01 μF chip capacitor as shown in Figure 20.

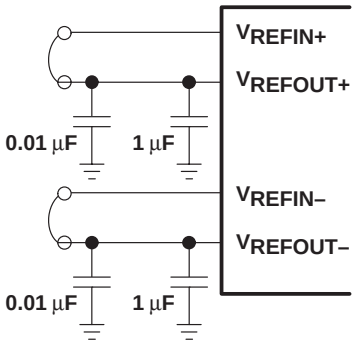


Figure 19. Internal Reference Usage

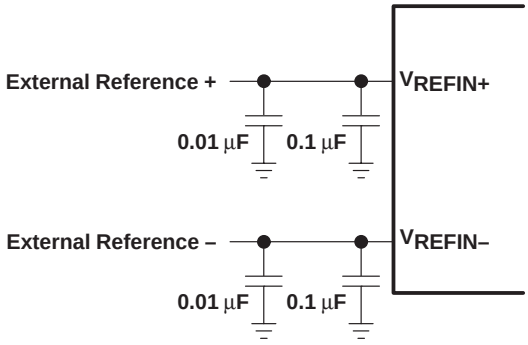


Figure 20. External Reference Usage

using the THS1060 clock input

The THS1060 is a high performance A/D converter. In order to obtain the best possible performance, care should be taken to ensure that the device is clocked appropriately. The optimal clock to the device is a low jitter square wave with sharp rise times (<2ns) at 50% duty cycle. The two clock inputs (CLK+ and CLK–), should be driven with complimentary signals that have minimal skew, and nominally swing between 0 V and 5 V. The device will still operate with a peak to peak swing of 3 V on each clock channel (around the 2.5 V midpoint), but it could become more duty cycle sensitive under such conditions.

Use of a transformer coupled clock input ensures minimal skew between the CLK+ and CLK– signals. If the available clock signal swing is not adequate, a step-up transformer can be used in order to deliver the required levels to the converter's inputs, see Figure 21. For example if a 3.3 V standard CMOS logic is used for clock generation, a minicircuits T4–1H transformer can be used for 2x voltage step-up. This provides greater than 6 V differential swing at the secondary of the transformer, which provides greater than 3 V swings to both CLK+ and CLK– terminals of THS1060. The center tap of the transformer secondary is connected to the V_{CM} terminal of the THS1060 for proper dc biasing.

Both the transformer and the clock source should be placed close to THS1060 to avoid transmission line effects. 3.3 V TTL logic is not recommended with T4–1H transformer due to TTLs tendency to have lower output swings. If the input to the transformer is a square wave (such as one generated by a digital driver), care must be taken to ensure that the transformer's bandwidth does not limit the signal's rise time and effectively alter its shape and duty cycle characteristics. For a 60 MSPS rate, the transformer's bandwidth should be at least 300 MHz. A low phase noise sinewave can also be used to effectively drive the THS1060. In this case, the bandwidth of the transformer becomes less critical, as long as it can accommodate the frequency of interest (for example, 60 MHz). The turns ratio should be chosen to ensure appropriate levels at the device's input. If the clock signal is fed through a transmission line of characteristic impedance Zo , then the secondary of the transformer should be terminated with a resistor of nZo , where n is the transformer's impedance ratio (1:n) as shown in Figure 21. Alternatively a series termination can be used at the clock source.

APPLICATION INFORMATION

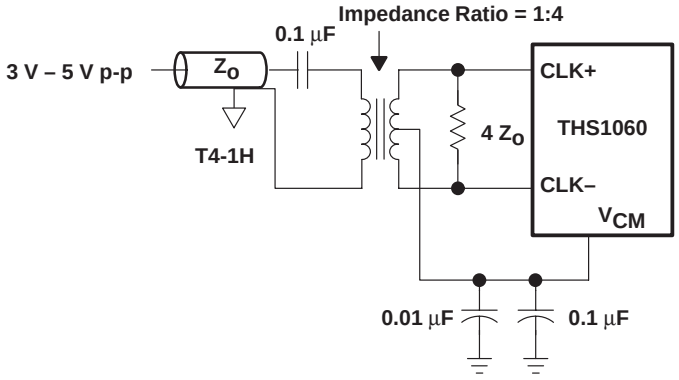


Figure 21. Coaxial Clock Source

The clock signals, CLK+ and CLK– should be well matched and must both be driven.

A transformer ensures minimal skew between the two complementary channels. However, skew levels of up to 500 ps between CLK+ and CLK– can be tolerated with some performance degradation.

The clock input can also be driven differentially with a 5 V TTL signal by using an RF transformer to convert the TTL signal to a differential signal. The TTL signal is ac coupled to the positive primary terminal with a high pass circuit. The negative terminal of the transformer is connected to ground (see Figure 22). The transformer secondary is connected to the CLK inputs.

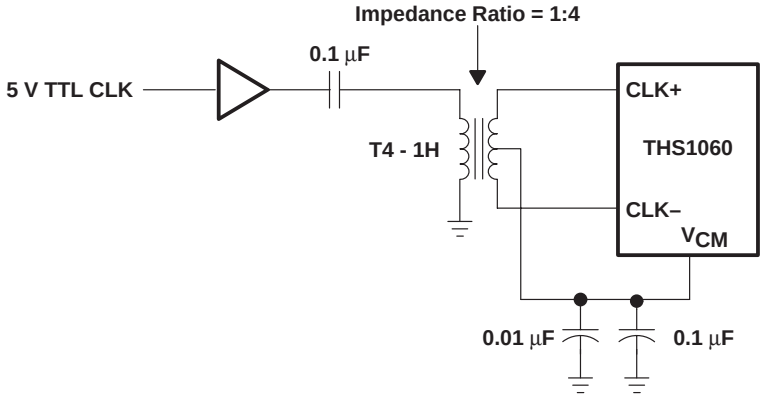


Figure 22. TTL Clock Input

APPLICATION INFORMATION

using the analog input

The THS1060 obtains optimum performance when the analog signal inputs are driven differentially. The circuit below shows the optimum configuration, see Figure 23. The signal is fed to the primary of an RF transformer. Since the input signal must be biased around the common mode voltage of the internal circuitry, the common mode (V_{CM}) reference from the THS1060 is connected to the center-tap of the secondary. To ensure a steady low noise V_{CM} reference the best performance is obtained when the V_{CM} output is connected to ground with a 0.1 μF and 0.01 μF low inductance capacitor.

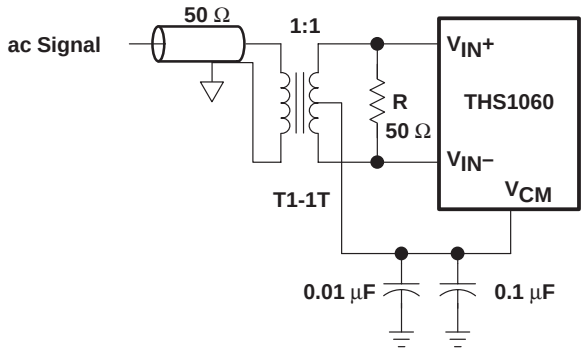


Figure 23. THS1060 With Coaxial Feed

When it is necessary to buffer or apply a gain to the incoming analog signal, it is also possible to combine a single-ended amplifier with an RF transformer as shown in Figure 24. For this application, a wide-band current mode feedback amplifier such as the THS3001 is best. The single ended output allows the use of standard passive filters between the amplifier output and the primary. In this case, the SFDR of the op amp is not as critical as that of the A/D converter. While harmonics generated from within the A/D converter fold back into the first Nyquist zone, harmonics generated externally in the op amps can be filtered out with passive filters.

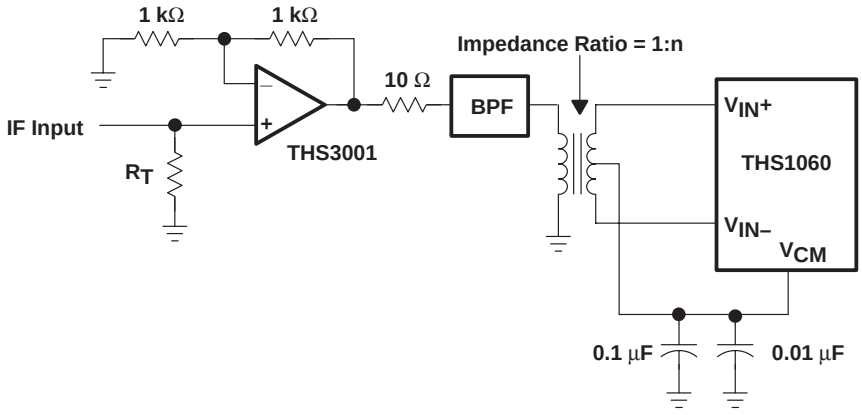


Figure 24. IF Input Buffered with THS3001 Op Amp

APPLICATION INFORMATION

digital outputs

The digital outputs can drive either TTL or 5-V CMOS inputs when DRV_{DD} = 5 V. To reduce capacitive loading, each digital output of the THS1060 should drive only one digital input. The CMOS output drivers are capable of handling up to a 15 pF load. For better SNR performance, use 3.3 V for DRV_{DD}. Resistors of 200-Ω in series with the digital output can be used for optimizing SNR performance.

power supplies

Best performance is obtained when AV_{DD} is kept separate from DV_{DD}. Regulated or linear supplies, as opposed to switched power supplies, must be used to minimize supply noise. It is also recommended to partition the analog and digital components on the board in such a way that the analog supply plane does not overlap with the digital supply plane in order to limit dielectric coupling between the different supplies.

using the TI PowerPAD™

While it is not necessary to use the Texas Instruments PowerPAD™ to meet the minimum and maximum specs indicated in this spec sheet, proper use of the PowerPAD™ will improve the performance of the THS1060 especially at T_A = 85°C.

For high speed sampling applications (around 60 MSPS), significant performance enhancement above the specified values can be achieved by properly applying the PowerPAD™. This will maintain the junction temperature of the device at significantly lower levels and render the device even more insensitive to duty cycle variations on the clock, as shown in Figure 18.

The THS1060 package makes use of the Texas Instruments PowerPAD™ which, when soldered to a thermal land, creates a highly efficient path for heat energy and ground noise currents from the circuit die to the PCB ground plane. The silicon die in a PowerPAD™ package is bonded to a copper alloy plate with a thin layer of thermally and electrically conductive epoxy. The copper alloy plate or PowerPAD™ is exposed on the bottom of the device package for a direct solder attachment to a PCB land or conductive pad. The land dimensions should have minimum dimensions equal to the package dimensions minus 2 mm, see Figure 25.

For a multilayer circuit board, a second land having dimensions equal to or greater than the land to which the device is soldered should be placed on the back of the circuit board (see Figure 26). A total of 9 thermal vias or plated through-holes should be used to connect the two lands to a ground plane (buried or otherwise) having a minimum total area of 3 inches square in 1 oz. copper. For the THS1060 package, the thermal via centers should be spaced at a minimum of 1 mm. The ground plane need not be directly under or centered around the device footprint if a wide ground plane thermal run having a width on the order of the device is used to channel the heat from the vias to the larger portion of the ground plane. The THS1060 package has a standoff of 0.19 mm or 7.5 mils. In order to apply the proper amount of solder paste to the land. a solder paste stencil with a 6 mils thickness is recommended for this device. Too thin a stencil may lead to an inadequate connection to the land. Too thick a stencil may lead to beading of solder in the vicinity of the pins which may lead to shorts. For more information, refer to Texas Instruments literature number SLMA002 *PowerPAD™ Thermally Enhanced Package*.

APPLICATION INFORMATION

using the TI PowerPAD™ (continued)

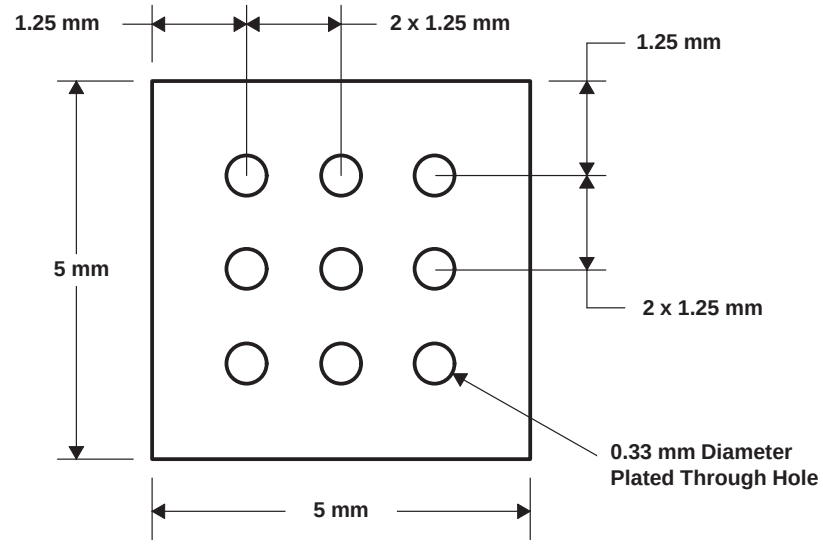


Figure 25. Thermal Land (top view)

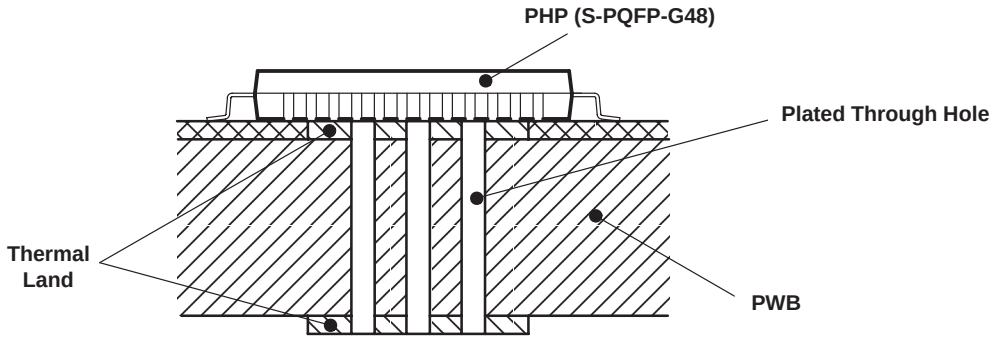
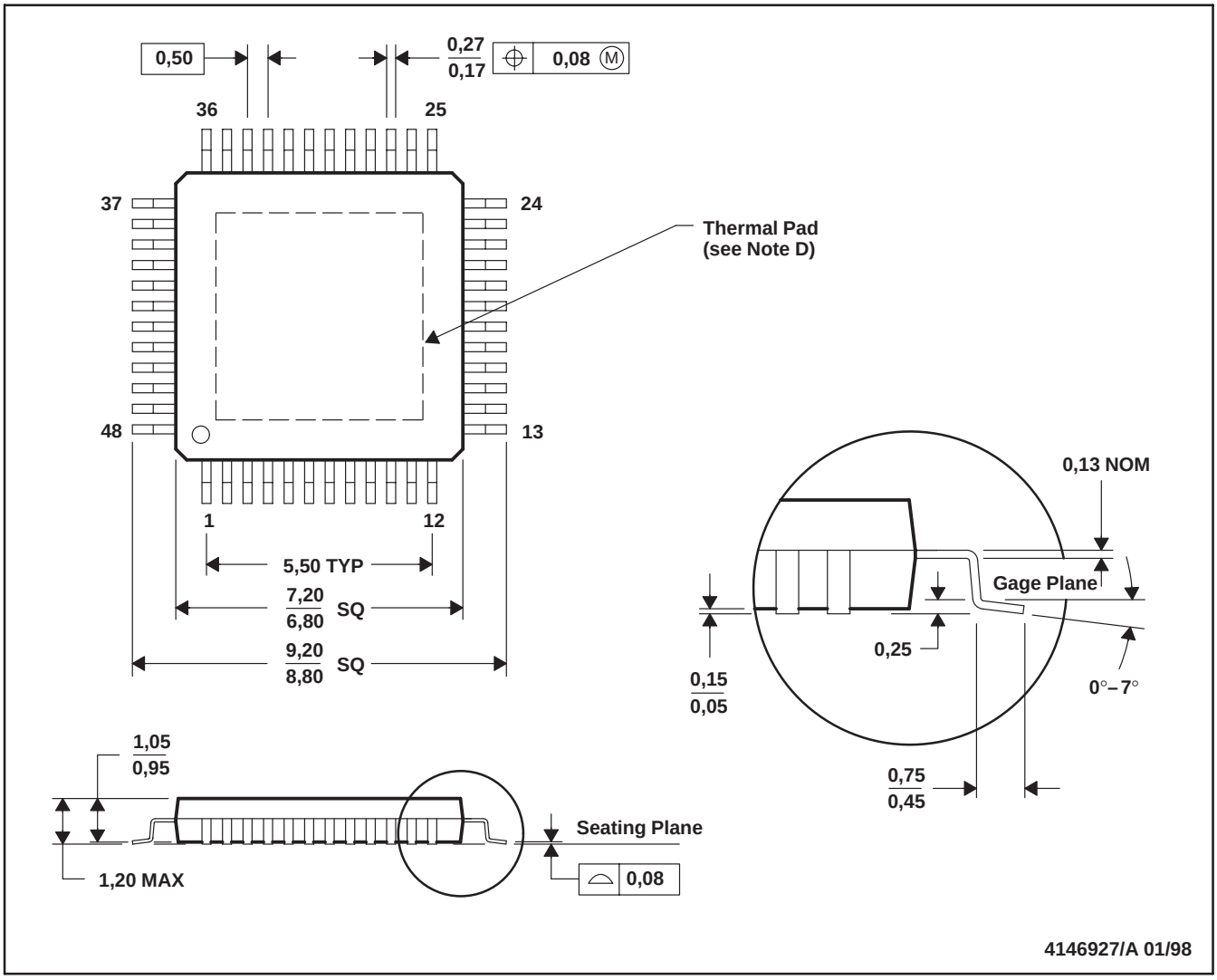


Figure 26. Top and Bottom Thermal Lands With Plated Through Holes (side view)

MECHANICAL DATA

PHP (S-PQFP-G48) **PowerPAD™ PLASTIC QUAD FLATPACK**



NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusions.
D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
E. Falls within JEDEC MO-153

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